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(54) **Title:** MICROELECTRONIC DEVICE, STACKED DIE PACKAGE AND COMPUTING SYSTEM CONTAINING SAME, METHOD OF MANUFACTURING A MULTI-CHANNEL COMMUNICATION PATHWAY IN SAME, AND METHOD OF ENABLING ELECTRICAL COMMUNICATION BETWEEN COMPONENTS OF A STACKED-DIE PACKAGE

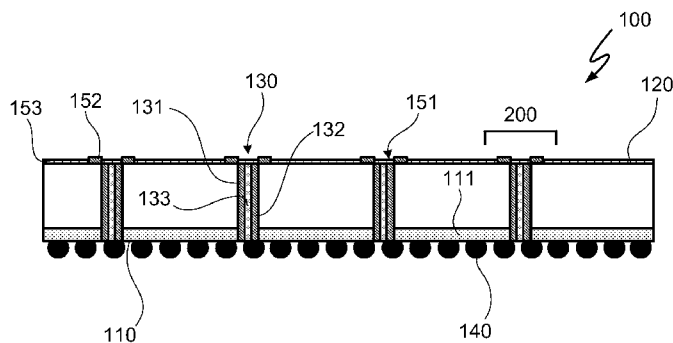


FIG. 1

(57) **Abstract:** A microelectronic device comprises a first surface (110, 710), a second surface (120, 720), and a passageway (130, 730) extending from the first surface to the second surface. The passageway contains a plurality of electrically conductive channels (131, 132, 231, 232) separated from each other by an electrically insulating material (133, 1333).

